**ICEP Presentation Number and Year:**

e.g., AA1-1, 2024

**Classifications：**

e.g., MEMS, Power electronics

**Title：**

A Method to …

**Running Title(within 70 characters including spaces)：**

Method …..

**ABSTRACT(within 200 words)：**

An improved method for…

**Keywords(5 to 10 keywords)**：

Non-Conductive Film, Flexible Printed Circuits, …

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**Body：**

**1．Introduction**

As electronic devices become multi-functionalized～～using NCF.[1, 2] …

Table 1　xxxx

|  |  |
| --- | --- |
| A | 1111 |
| B | 2222 |
| C | 3333 |

(300dpi resolution is recommended for non‐vector graphics for color and grayscale images and 600dpi for black and white line art.)

Fig. 1　xxxxx

**References**

[1] H. Suzuki, Y. Ikuta and M. Kawabata, “Junction of the Flexible Printed Circuit using Anisotropic Conductive

Film”, Proceedings MES2003, pp. 352–355, 2003.

[2] H. Kristiansen and A. Borneklett, “Finepitch connection to rigid substrate using nonconductive epoxy adhesive”, J. Electronics Manufacturing, Vol. **2**, pp. 7–12, 1992.

**Figure captions**

Fig. 1 Schematic model of dendric plating method.

Fig. 2 ~~

**Author photo & brief biography (about 90 words)**